

NOVI nAg25

nano-silver connections



TECHNICAL DATA SHEET:

Product Description

NOVI nano-silver connections paste is designed for screen printing on rigid and flexible substrates. It can be used for preparing conductive joints in Low Temperature Joining Technique. It is an excellent product for high power electronics

It is possible to adjust the properties of the paste to the customer's needs.

Product benefits

- ✓ *Low electrical resistivity*
- ✓ *High thermal conductivity*
- ✓ *Good shear strength resistance*
- ✓ *Excellent for high Power electronics*

Processing:

materials tested as possible substrates:

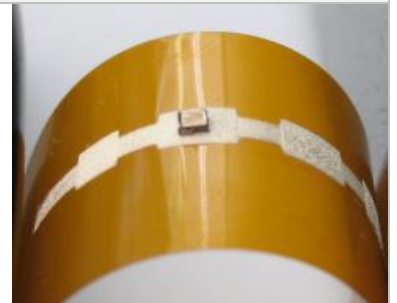
Silica, Aluminum, Copper, Glass, Kapton foil,

designed for technologies:

screen printing

important processing parameters:

- instrumentation: manual or semiautomatic screen printing
- types of sieves: steel or polyester, 200 - 250 mesh,
- sintering in 300 °C with 5 MPa pressure



Composition:

- Functional phase: silver nanoparticles
- Washing solvent: acetone
- Organic vehicle and solvent

Important joint parameters:

- **Resistivity:** $4 \cdot 10^{-8} \Omega m$
- **Thermal conductivity:** $\cdot 190 W/mK$
- **Shear strength resistance:** $20 MPa$
- **Thickness of the layer after sintering:** $\cdot 10-15 \mu m$
- **Layer work temperature:** $600 \text{ }^\circ C$

Storage and shelf life:

Tightly sealed containers should be stored in a dry room, at room temperature, away from sources of fire. Shelf life for pastes in unopened containers is 6 months from the date of production. Sedimentation symptoms may appear; stir the paste thoroughly before use.



For details, contact:

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